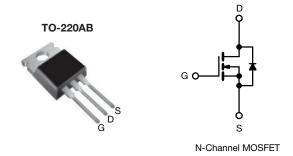


Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	100				
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V 0.54				
Q _g max. (nC)	8.3				
Q _{gs} (nC)	2.3				
Q _{gd} (nC)	3.8				
Configuration	Single				



FEATURES

- Dynamic dV/dt rating
- · Repetitive avalanche rated
- 175 °C operating temperature
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF510PbF		
	SiHF510-E3		
SnPb	IRF510		
	SiHF510		

ABSOLUTE MAXIMUM RATINGS (T_C	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	100	.,,	
Gate-Source Voltage			V_{GS}	± 20	V	
Continuous Drain Current	V -140.V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$		5.6		
	V _{GS} at 10 V	T _C = 100 °C	I _D	4.0	Α	
Pulsed Drain Current a			I _{DM}	20		
Linear Derating Factor				0.29	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	75	mJ	
Repetitive Avalanche Current a			I _{AR}	5.6	А	
Repetitive Avalanche Energy a			E _{AR}	4.3	mJ	
Maximum Power Dissipation $T_C = 25 ^{\circ}C$			P_{D}	43	W	
Peak Diode Recovery dV/dt ^c	dV/dt	5.5	V/ns			
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C	
Soldering Recommendations (Peak temperature) ^d for 10 s				300		
Maunting Tayous	6-32 or M3 screw			10	lbf ⋅ in	
Mounting Torque			Ī	1.1	N⋅m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. $V_{DD}=25$ V, starting $T_J=25$ °C, L=4.8 mH, $R_g=25$ Ω , $I_{AS}=5.6$ A (see fig. 12). c. $I_{SD}\leq5.6$ A, $dI/dt\leq75$ A/µs, $V_{DD}\leq V_{DS}$, $T_J\leq175$ °C.

- d. 1.6 mm from case.



Vishay Siliconix

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-	62			
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50	-	°C/W		
Maximum Junction-to-Case (Drain)	R _{thJC}	-	3.5			

SPECIFICATIONS (T _J = 25 °C, t	ınless otherw	ise noted)					
PARAMETER	SYMBOL	TEST (MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _D = 1 mA	-	0.12	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V$	_{GS} , I _D = 250 μA	2.0	-	4.0	٧
Gate-Source Leakage	I _{GSS}	V _G	V _{GS} = ± 20 V		-	± 100	nA
	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V		-	-	25	μА
Zero Gate Voltage Drain Current		V _{DS} = 80 V, V	V _{DS} = 80 V, V _{GS} = 0 V, T _J = 150 °C		-	250	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D =3.4 A ^b	-	-	0.54	Ω
Forward Transconductance	9 _{fs}	V _{DS} = 5	0 V, I _D = 3.4 A ^b	1.3	-	-	S
Dynamic	l	1			1	l.	
Input Capacitance	C _{iss}	V	_{GS} = 0 V,	-	180	-	
Output Capacitance	C _{oss}	1 v	$V_{DS} = 25 \text{ V},$		81	-	pF
Reverse Transfer Capacitance	C _{rss}	7	MHz, see fig. 5	-	15	-	Pi
Total Gate Charge	Q_g		I _D = 5.6 A, V _{DS} = 80 V	-	-	8.3	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	V _{DS} = 10 V,	-	-	2.3	nC
Gate-Drain Charge	Q_{gd}		see fig. 6 and fig. 13 b	-	-	3.8	
Turn-On Delay Time	t _{d(on)}	V_{DD} = 50 V, I_{D} = 5.6 A R_{g} = 24 Ω , R_{D} = 8.4 Ω , see fig. 10 ^b		-	6.9	-	ns
Rise Time	t _r			1	16	-	
Turn-Off Delay Time	t _{d(off)}			-	15	-	
Fall Time	t _f			1	9.4	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from	_ ,		4.5	-	
Internal Source Inductance	L _S	package and cer die contact	package and center of		7.5	-	nH
Drain-Source Body Diode Characteristic	cs	1					1
Continuous Source-Drain Diode Current	Is	MOSFET symbo showing the	MOSFET symbol showing the			5.6	_
Pulsed Diode Forward Current ^a	I _{SM}	integral reverse p - n junction diode		-	-	20	A
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S	$T_J = 25$ °C, $I_S = 5.6$ A, $V_{GS} = 0$ V b		-	2.5	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 5.6 A, dI/dt = 100 A/µs b		-	100	200	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	0.44	0.88	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)				L _D)	
	1						

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

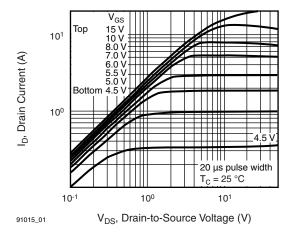


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

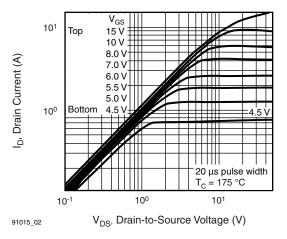


Fig. 2 - Typical Output Characteristics, $T_C = 175$ °C

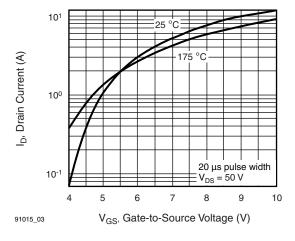


Fig. 3 - Typical Transfer Characteristics

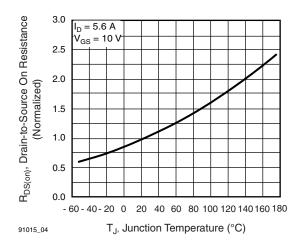


Fig. 4 - Normalized On-Resistance vs. Temperature

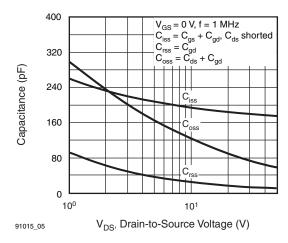


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

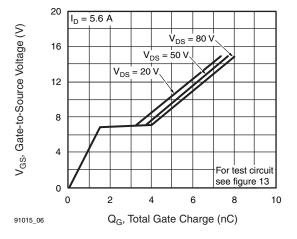


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



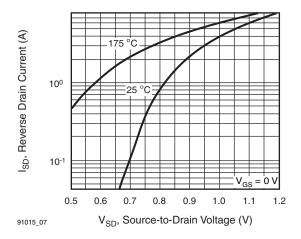


Fig. 7 - Typical Source-Drain Diode Forward Voltage

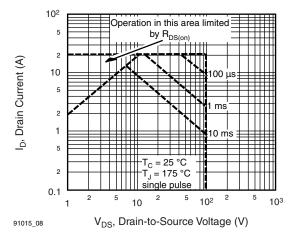


Fig. 8 - Maximum Safe Operating Area

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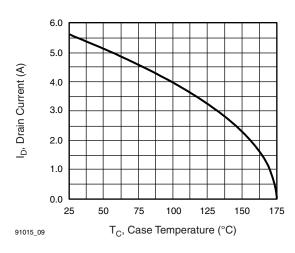


Fig. 9 - Maximum Drain Current vs. Case Temperature

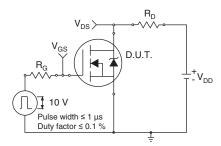


Fig. 10a - Switching Time Test Circuit

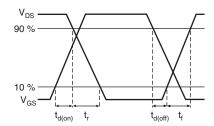


Fig. 10b - Switching Time Waveforms

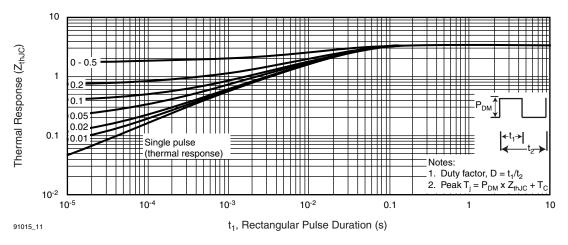


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



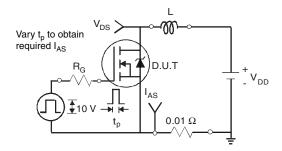


Fig. 12a - Unclamped Inductive Test Circuit

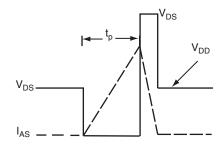


Fig. 12b - Unclamped Inductive Waveforms

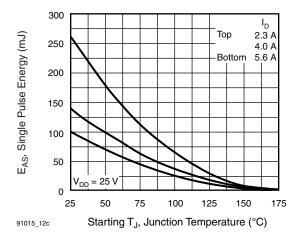


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

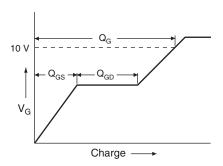


Fig. 13a - Basic Gate Charge Waveform

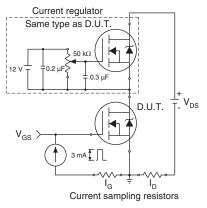
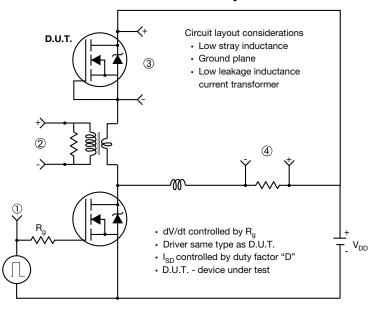


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



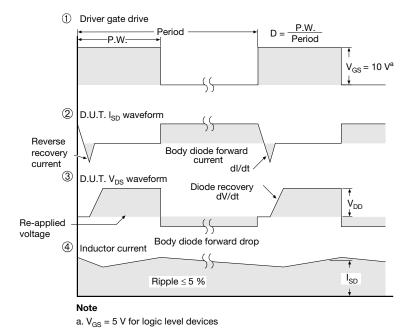


Fig. 14 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91015.





TO-220-1



DIM	MILLIN	IETERS	INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	4.24	4.65	0.167	0.183		
b	0.69	1.02	0.027	0.040		
b(1)	1.14	1.78	0.045	0.070		
С	0.36	0.61	0.014	0.024		
D	14.33	15.85	0.564	0.624		
E	9.96	10.52	0.392	0.414		
е	2.41	2.67	0.095	0.105		
e(1)	4.88	5.28	0.192	0.208		
F	1.14	1.40	0.045	0.055		
H(1)	6.10	6.71	0.240	0.264		
J(1)	2.41	2.92	0.095	0.115		
L	13.36	14.40	0.526	0.567		
L(1)	3.33	4.04	0.131	0.159		
ØР	3.53	3.94	0.139	0.155		
Q	2.54	3.00	0.100	0.118		
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031						

Note

 \bullet $M^{\star}=0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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